CHIPQUIK® WWSWLT.040 200g

Datasheet revision 1.0 www.chipquik.com

Sn42/Bi57/Ag1 2.5% No-Clean Water-Washable Flux Core Solder Wire 1.0mm 200g

Product Highlights

LOW TEMPERATURE WITH FLUX CORE
Melts at 138°C (281°F)
No-Clean Water-Washable
2.5% flux core
Lead-Free
RoHS 3 and REACH compliant

Specifications

Alloy:	Sn42/Bi57/Ag1
Wire diameter:	0.040” (1.0mm)
Flux Core:	2.5% No-Clean Water-Washable
Flux Classification:	REL0
Melting Point:	138°C (281°F)
Packaging:	200g (7.0oz) Spool
Shelf Life:	>60 months

Storage and Handling

Store in a non-corrosive, dry environment.

Please Note: Although Sn42/Bi57/Ag1 forms strong joints and is more ductile due to the added 1% Silver, in wire form it is brittle and needs to be handled gently when unspooling. It is normal for spooled Sn42/Bi57/Ag1 wire to have some breaks in it.

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes

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